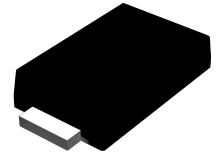


## Features

- Low forward voltage drop
- Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Low profile, typical thickness 1.0mm
- Solder dip 260 °C, 10 s
- AEC-Q101 qualified



Package: eSMB(SMAF)

## Applications

For uses in low voltage, high frequency inverters, free wheeling and polarity protection applications.

## Maximum Ratings (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Symbol	LSL36	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	60	V
Maximum RMS Voltage	V <sub>RMS</sub>	42	V
Maximum DC Blocking Voltage	V <sub>DC</sub>	60	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3.0	A
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I <sub>FSM</sub>	100	A
Operating Junction Temperature Range	T <sub>J</sub>	- 55 to + 125	°C
Storage Temperature Range	T <sub>STG</sub>	- 55 to + 125	°C

## Electrical Characteristics (T<sub>A</sub> = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Instantaneous Forward Voltage	I <sub>F</sub> =1A, T <sub>A</sub> =25°C	V <sub>F</sub>	-	0.42	0.45	V
	I <sub>F</sub> =2A, T <sub>A</sub> =25°C		-	0.47	0.50	
	I <sub>F</sub> =3A, T <sub>A</sub> =25°C		-	0.51	0.55	
	I <sub>F</sub> =3A, T <sub>A</sub> =100°C		-	0.46	-	
Maximum DC Reverse Current at Rated DC Blocking Voltage	T <sub>A</sub> =25°C	I <sub>R</sub>	5			mA
	T <sub>A</sub> =100°C		100			
Typical Junction Capacitance	4.0 V, 1 MHz	C <sub>J</sub>	1320			pF
Typical Thermal Resistance <sup>1)</sup>	Junction to Lead	R <sub>θJL</sub>	30			°C/W

Note1: Thermal resistance from junction to lead, mounted on PCB with 8.0x 8.0mm copper pads

## Ratings and Characteristics Curves ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

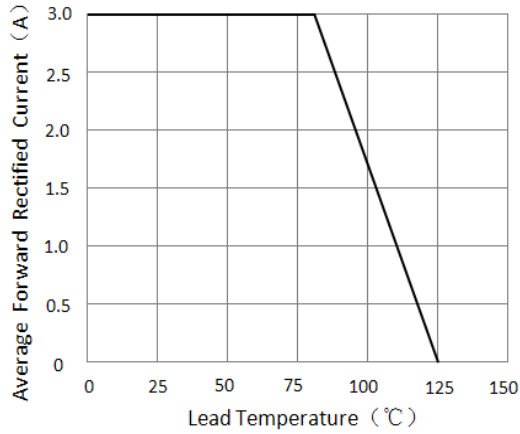


Figure 1. Forward Current Derating Curve

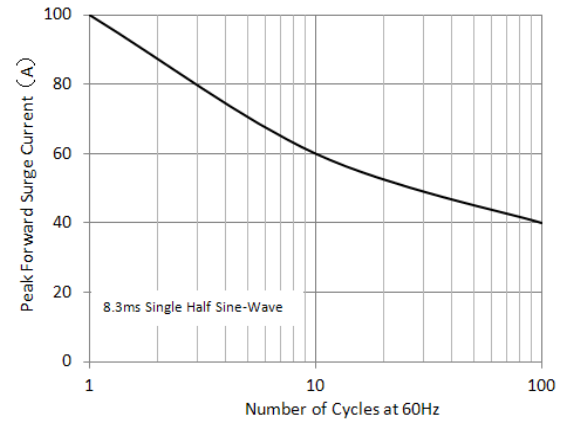


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

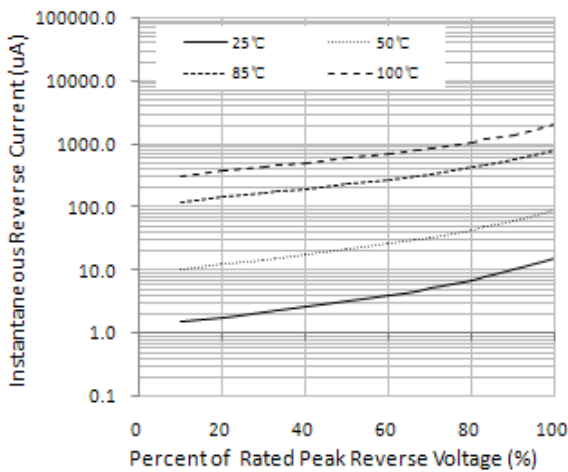


Figure 3. Typical Reverse Characteristics

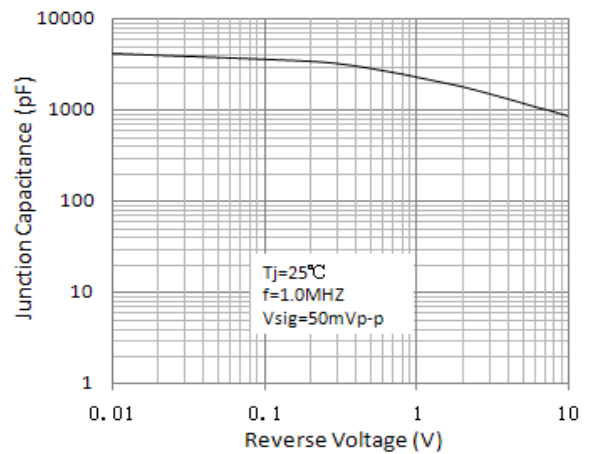


Figure 4. Typical Junction Capacitance

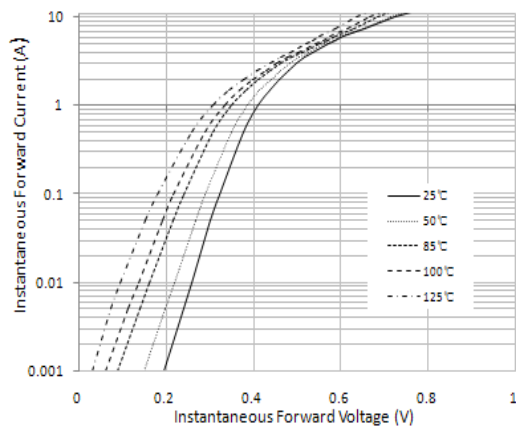
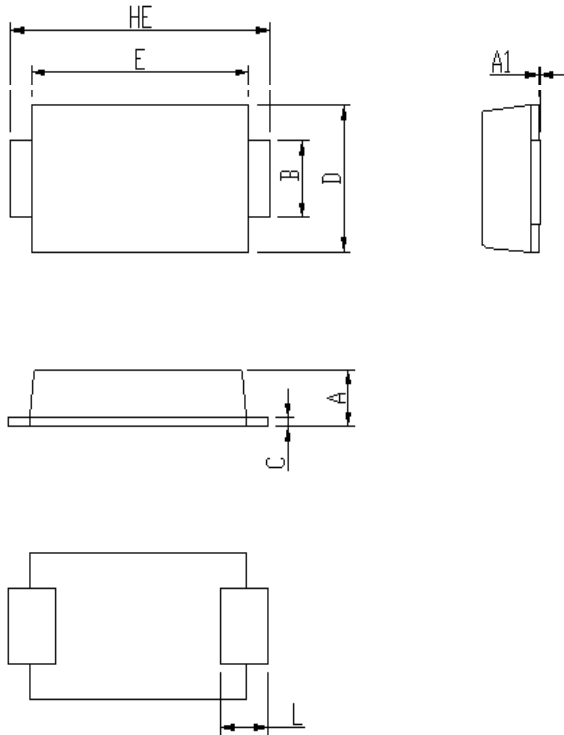


Figure 5. Typical Instantaneous Forward Characteristics

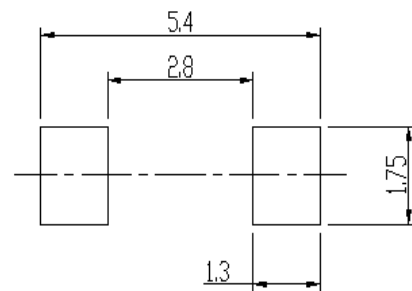
## Package Outline Dimensions

eSGB (SMAF)



DIM	Unit: mm		Unit: inch	
	MIN	MAX	MIN	MAX
A	0.92	1.08	0.036	0.043
A1	0	0.1	0.000	0.004
B	1.25	1.45	0.049	0.057
C	0.1	0.25	0.004	0.010
D	2.6	2.8	0.102	0.110
E	4.1	4.3	0.161	0.169
L	0.7	1.1	0.028	0.043
HE	4.8	5.2	0.189	0.205

Soldering footprint



## Packing Information

### Packing quantities:

10,000 pcs/Reel, 12mm Tape, 13" Reel

### Tape & Reel Specification

